

## ABSTRACT

A table for a wafer polishing apparatus having superior heat-resistant, anti-thermal-shock, and anti-abrasion characteristics and capable of increasing the diameter of a semiconductor wafer while improving the quality of the wafer. The table (2) includes a plurality of superimposed bases (11) each of which is formed of silicide ceramic or carbide ceramic. The bases (11) are joined together by an adhesive layer (14). A fluid passage (12) is formed in a joining interface between the bases (11).